

AMENDMENTS TO THE CLAIMS:

1. (Previously Amended) A tape carrier type semiconductor device comprising:
a flexible substrate on whose surface wiring is formed; and
a driver circuit which is mounted on said flexible substrate and drives a device
connected to said flexible substrate,

B1 wherein said flexible substrate includes a first slit having a connector situated
intermediate thereto for connecting both sides of the first slit to reduce warpage, and

wherein said first slit comprises a first sub-slit and a second sub-slit with said
connector therebetween.

2. (Original) The tape carrier type semiconductor device according to claim 1, wherein
the first slit includes a plurality of connectors.

3. (Original) The tape carrier type semiconductor device according to claim 2, wherein
parts of the slit, which are separated from each other at the connector, are diverged from each
other at the connector in a direction perpendicular to the slit.

4. (Original) The tape carrier type semiconductor device according to claim 3, wherein
said flexible substrate includes a plurality of first slits.

5. (Original) The tape carrier type semiconductor device according to claim 4, wherein
said flexible substrate includes a second slit for folding said tape carrier type semiconductor
device.

6. (Currently Amended) The tape carrier type semiconductor device according to claim 54, wherein said flexible substrate includes a said rib which is formed substantially perpendicular to the plurality of first slits.

7. (Original) The tape carrier type semiconductor device according to claim 6, a portion of said flexible substrate is changed in shape, thereby to form the rib.

8. (Previously Amended) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate includes a rib formed substantially perpendicular to the first slit.

9. (Currently Amended) The tape carrier type semiconductor device according to claim 81, wherein a portion of said flexible substrate is changed in shape, thereby to form the rib.

10. (Previously Amended) A tape carrier type semiconductor device comprising:

a flexible substrate on whose surface wiring is formed; and

a driver circuit which is mounted on said flexible substrate and drives a device connected to said flexible substrate,

wherein said flexible substrate includes a first slit for folding said flexible substrate and a rib formed substantially perpendicular to the first slit, and

wherein said first slit comprises a first sub-slit and a second sub-slit with a connector therebetween to reduce warpage.

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cont.

11. (Original) The tape carrier type semiconductor device according to claim 10, a portion of said flexible substrate is changed in shape, thereby to form the rib.

12. (Canceled)

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cont.
13. (Previously Amended) A flexible substrate, comprising:
a first slit having a connector thereto for connecting both sides ends of the first slit to reduce warpage, and on whose surface wiring having a predetermined pattern is formed,
wherein said first slit comprises a first sub-slit and a second sub-slit with said connector therebetween.

14. (Original) The flexible substrate according to claim 13, wherein the first slit includes a plurality of connectors.

15. (Original) The flexible substrate according to claim 14, wherein parts of the slit, which are separated from each other at the connector, are diverged from each other at the connector in a direction perpendicular to the slit.

16. (Original) The flexible substrate according to claim 15, further comprising a second slit for folding said flexible substrate.

17. (Original) The flexible substrate according to claim 16, further comprising a rib formed substantially perpendicular to the first slit.

18. (Currently Amended) The flexible substrate according to claim ~~17~~ 13, wherein a portion of said flexible substrate is changed in shape, thereby to form the rib.

19. (Previously added) The tape carrier type semiconductor device according to claim 1, wherein said connector comprises a bridge arranged at the center of said first slit.

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Cont. 20. (Previously added) The tape carrier type semiconductor device according to claim 1, wherein said first slit comprises a stress-releasing slit.

21. (Previously added) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises at least one of a polyimide resin film, an organic polymer film, a polyamide resin film, a polyester resin film and a composite film.

22. (Previously added) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a terminal area adjacent said first slit.

23. (Previously added) The tape carrier type semiconductor device according to claim 22, wherein said first slit is situated between said driver circuit and said terminal area, said first slit comprises a rectangular shape with a longitudinal side parallel to said terminal area.

24. (Currently Amended) The tape carrier type semiconductor device according to claim 1, wherein a said warpage of said tape carrier type semiconductor device is no more ~~then~~ than approximately 4.8% of a length of said tape carrier type semiconductor device.

25. (Previously added) The tape carrier type semiconductor device according to claim 10, wherein said first slit is for releasing stress, said first slit is substantially perpendicular to said rib.

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26. (Previously added) The tape carrier type semiconductor device according to claim 1, wherein said flexible substrate comprises a resin on a first side of said flexible substrate, said resin including a first heat expansion coefficient.

27. (Previously added) The tape carrier type semiconductor device according to claim 26, wherein said flexible substrate comprises a solder resist on a second side of said flexible substrate, said solder resist including a second heat expansion coefficient.

28. (Currently Amended) The tape carrier type semiconductor device according to claim 1, wherein said rib is comprises a reinforcement rib.

29. (Currently Amended) The tape carrier type semiconductor device according to claim 1, wherein said rib is has at least one of a concave and a convex shape.
